

FEATURES

- Glass passivated device
- Ideal for surface mounted applications
- Low leakage current
- Metallurgically bonded construction
- High temperature soldering:
/10 seconds at terminals

Mechanical Data

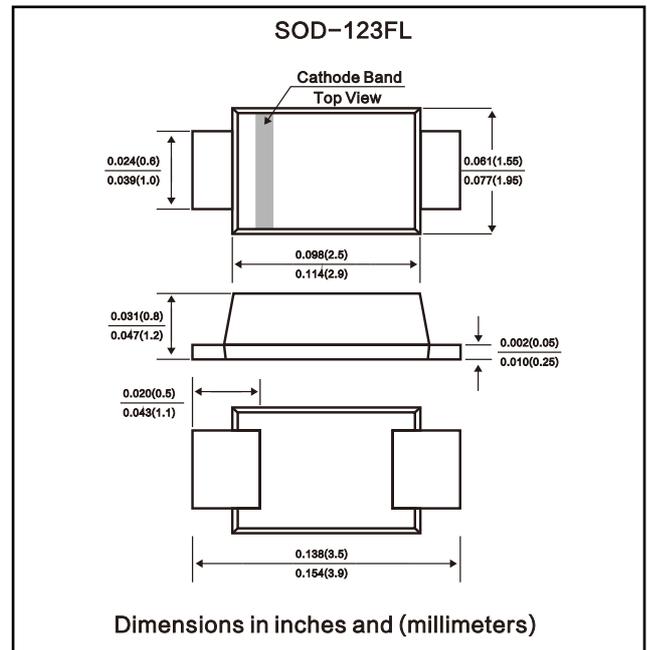
Case: JEDEC SOD-123FL, molded plastic over passivated chip

Terminals: Solder Plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Weight: 0.0008 ounces, 0.022 gram

Mounting position: Any


MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

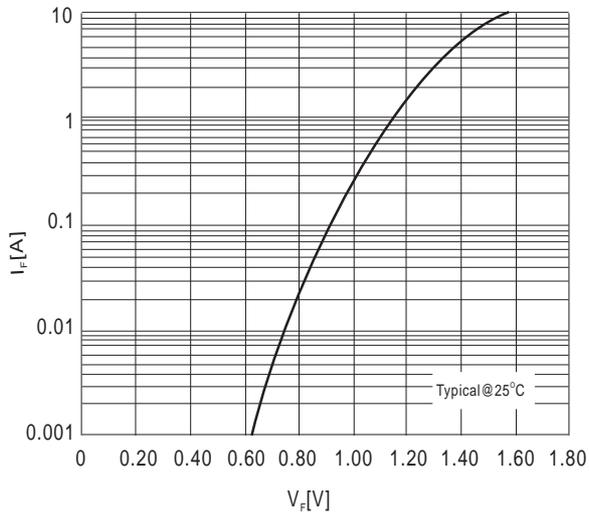
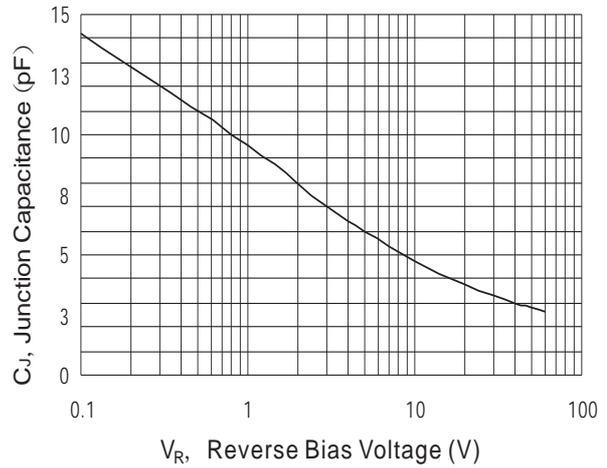
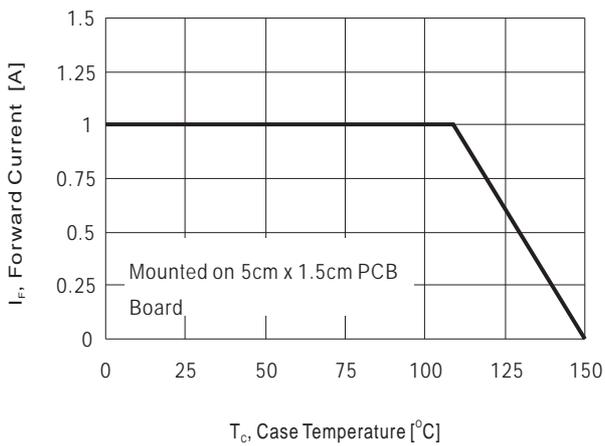
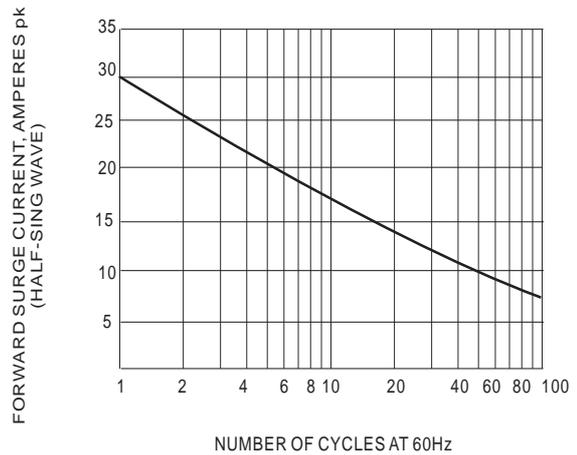
Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

PARAMETER	Symbol	US1001FL	US1002FL	US1004FL	US1006FL	US1008FL	Units
Maximum repetitive peak reverse voltage	V_{RRM}	100	200	400	600	800	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	V
Maximum DC blocking voltage	V_{DC}	100	200	400	600	800	V
Maximum average forward rectified current	$I_{F(AV)}$				1.4		A
	$T_{\theta B}=65^{\circ}C$ $T_A=45^{\circ}C$				0.5		
Maximum DC reverse current at rated DC blocking voltage	I_R				10		μA
	$T_A=25^{\circ}C$ $T_A=125^{\circ}C$				50		
Operating junction and storage temperature range	T_J, T_{STG}				-50 TO + 150		$^{\circ}C$

ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

PARAMETER	Symbol	US1001FL	US1002FL	US1004FL	US1006FL	US1008FL	Units
Maximum instantaneous forward voltage	V_F	1		1.4	1.7		V
Maximum DC reverse current at rated DC blocking voltage	I_R				10		μA
	$T_A=25^{\circ}C$ $T_A=125^{\circ}C$				50		
Reverse recovery time at $I_F=0.5A, I_R=1A, I_{tr}=0.25A$	t_{rr}					100	ns
Typical capacitance	C_J				9		pF


Fig.1-TYPICAL FORWARD CHARACTERISTICS

Fig.2-TYPICAL JUNCTION CAPACITANCE

Fig.3-FORWARD CURRENT DERATING CURVE

Fig.4-MAXIMUM NON-REPEITIVE SURGE CURRENT